

DESCRIPTION

AP1110 is a linear, low current power amplifier in ISM band utilizing InGaP /GaAs HBT process. The AP1110 is well suitable to be used for portable, low current 2.4GHz WLAN applications as well as for BT (Bluetooth) Class1 applications. AP1110 is packaged in **2x2** compact profile. For WLAN application, it features low current of **85mA** at linear power of **18.5dBm**, gain of 26dB under 3.3V. For Bluetooth applications, it features of gain at 26 dB; typical power of **23dBm** and PAE of **40%** under 3.3V.

Major Applications

- Bluetooth Class 1
- IEEE 802.11b/g WLAN system
- WLAN Portable Devices
- WLAN USB Devices
- Other 2.4 GHz ISM Band

KEY FEATURES

WLAN Applications:

(Under Vc=3.3V, Vref=2.8V)

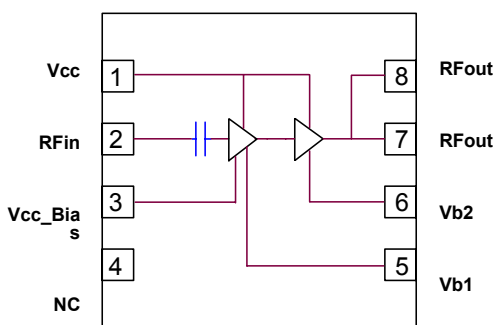
- **LOW Current:** 85mA at 18.5dBm
- **Ultra Small Profile:** 2x2(mm), DFN-8pin
- **High efficiency:**
PAE: 25% at 18dBm
- **Gain:** 26 dB

BT Applications:

(Under Vc=3.3V, Vref=2.85V)

- **LOW Current:** 140mA at 23dBm
95mA at 20dBm
50mA at 14dBm
- **Ultra Small Profile:** 2x2(mm), DFN-8pin
- **High efficiency:**
PAE: 40% at 23dBm
- **Gain:** 26 dB
- **Harmonic:** -33dBc at 23dBm

Functional Block Diagram



DFN - 8 pin, 2 x 2 (mm)

Pin Details

Pin Number	Name	Description
1	Vcc	Power Supply Input.
2	RFIn	RF input.
3	Vcc_Bias	Supply voltage for bias circuit.
4	NC	Non-connect.
5	Vb1	1 st -stage control voltage
6	Vb2	2 nd -stage control voltage
7	RFout	RF output. Require external matching. The detail configuration can be found in Application Notes
8	RFout	RF output. Require external matching. The detail configuration can be found in Application Notes
Package Base	Center Metal	The package ground provides circuit ground as well as heat dissipation path for the power amplifier.

© Outside circuit for WLAN and BT application, please refer to the AP1110 Application note for different BT application usage

For more information, please contact us at:

Sales Dept.

Tel: +886-2-2698-1022

e-mail: sales@rfintc.com

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Electrical Characteristics: WLAN Applications

Under $V_c=3.3V$, $V_{ref}=2.8V$, $T_a=25^\circ C$

PARAMETERS	CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Freq.		f	2.4		2.5	GHz
Total current	$P_{out}=18.5dBm$	I_{cc}		85		mA
Basic control reference current	$I_{cq}=21mA$	I_{ref}		0.5		mA
Power Gain	$P_{out}=18dBm$	G_p		26.5		dB
Quiescent current		I_{cq}		21		mA
Input VSWR				1.5		
Output VSWR				2		
Output power	EVM 3%	P_{out}		18.5		dBm
PAE		PAE		25		%

Absolute Maximum Ratings

Note:

Parameter	Rating	Unit
DC Power Supply For Collector	+5	V
DC Supply Current For Collector	280	mA
RF Input Power	+5	dBm
Operating Ambient Temperature	-40 to +85	$^\circ C$
Storage Temperature	-40 to +125	$^\circ C$

Important

The information provided in this datasheet is deemed to be accurate and reliable only at present time. RFIC Technology Corp. reserves the right to make any changes to the specifications in this datasheet without prior notice.

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Electrical Characteristics: BT Applications

Under $V_c=3.3V$, $V_{ref}=2.85V$, $T_a=25^\circ C$

PARAMETERS	CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Freq.		f	2.4		2.5	GHz
Total current	$P_{out}=23dBm$	I_{cc}		140		mA
	$P_{out}=20dBm$	I_{cc}		95		mA
	$P_{out}=14dBm$	I_{cc}		50		mA
Basic control reference current	$I_{cq}=18mA$	I_{ref}		0.5		mA
Power Gain	$P_{out}=20dBm$	G_p		26		dB
Quiescent current		I_{cq}		18		mA
Harmonic	$P_{out}=23dBm$	2f		-33		dBc
Input VSWR				2		
Output VSWR				2.5		
PAE	$P_{out}=23dBm$	PAE		40		%
Power		P_{1dB}		23		dBm

Absolute Maximum Ratings

Parameter	Rating	Unit
DC Power Supply For Collector	+5	V
DC Supply Current For Collector	280	mA
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Data Charts: WLAN Applications

Fig.1 – Pin, PAE and Icc vs. Pout

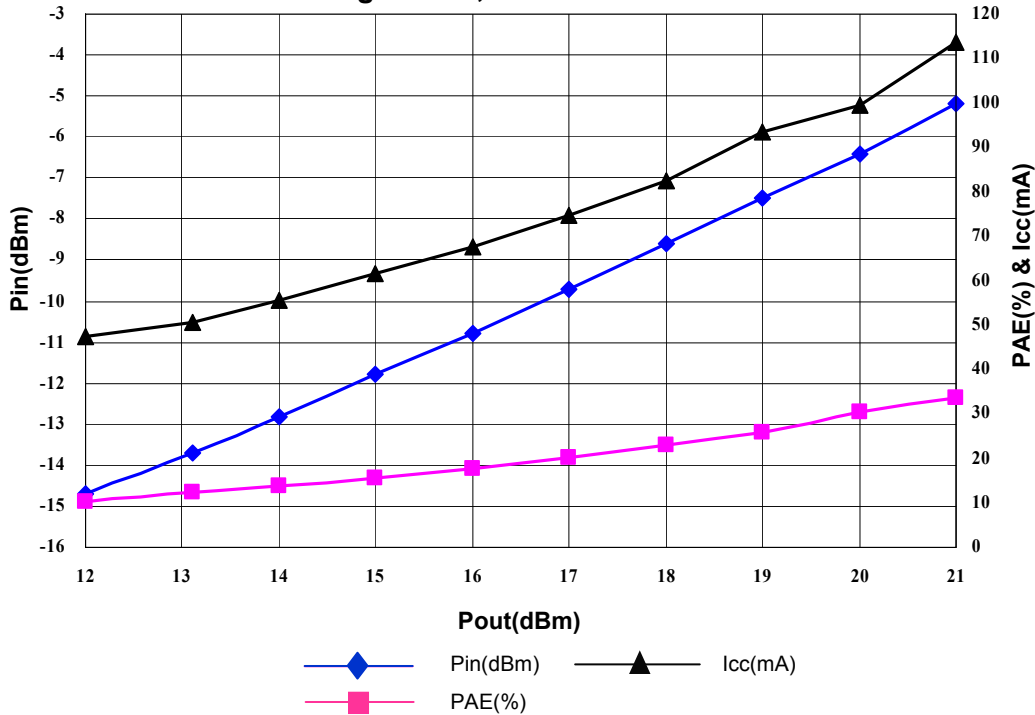
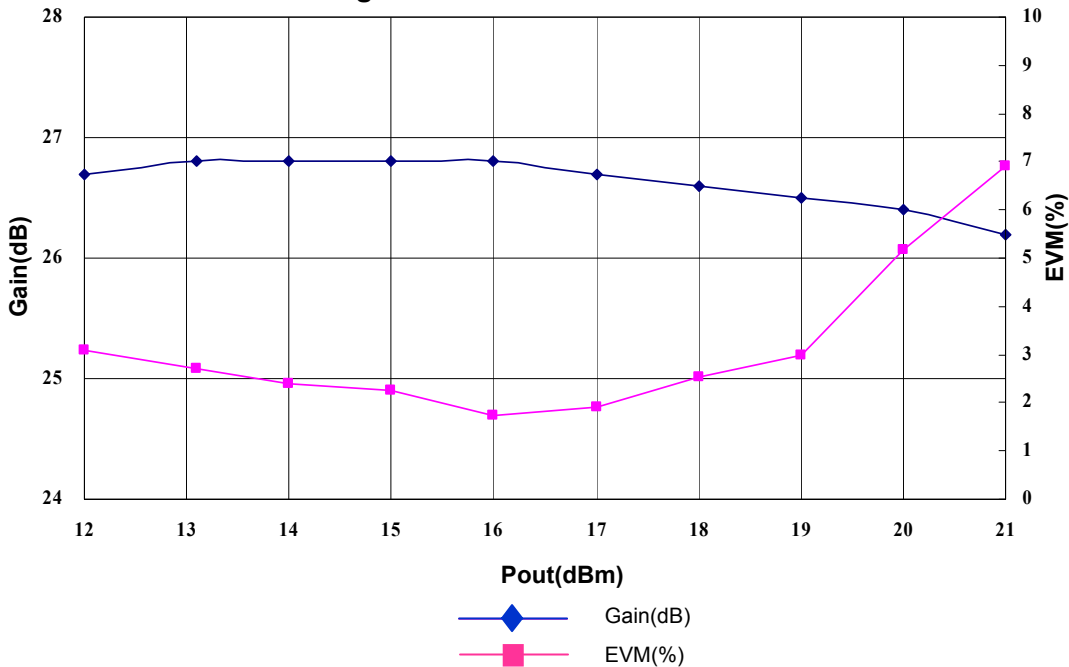


Fig.2 - Power Gain and EVM vs. Pout



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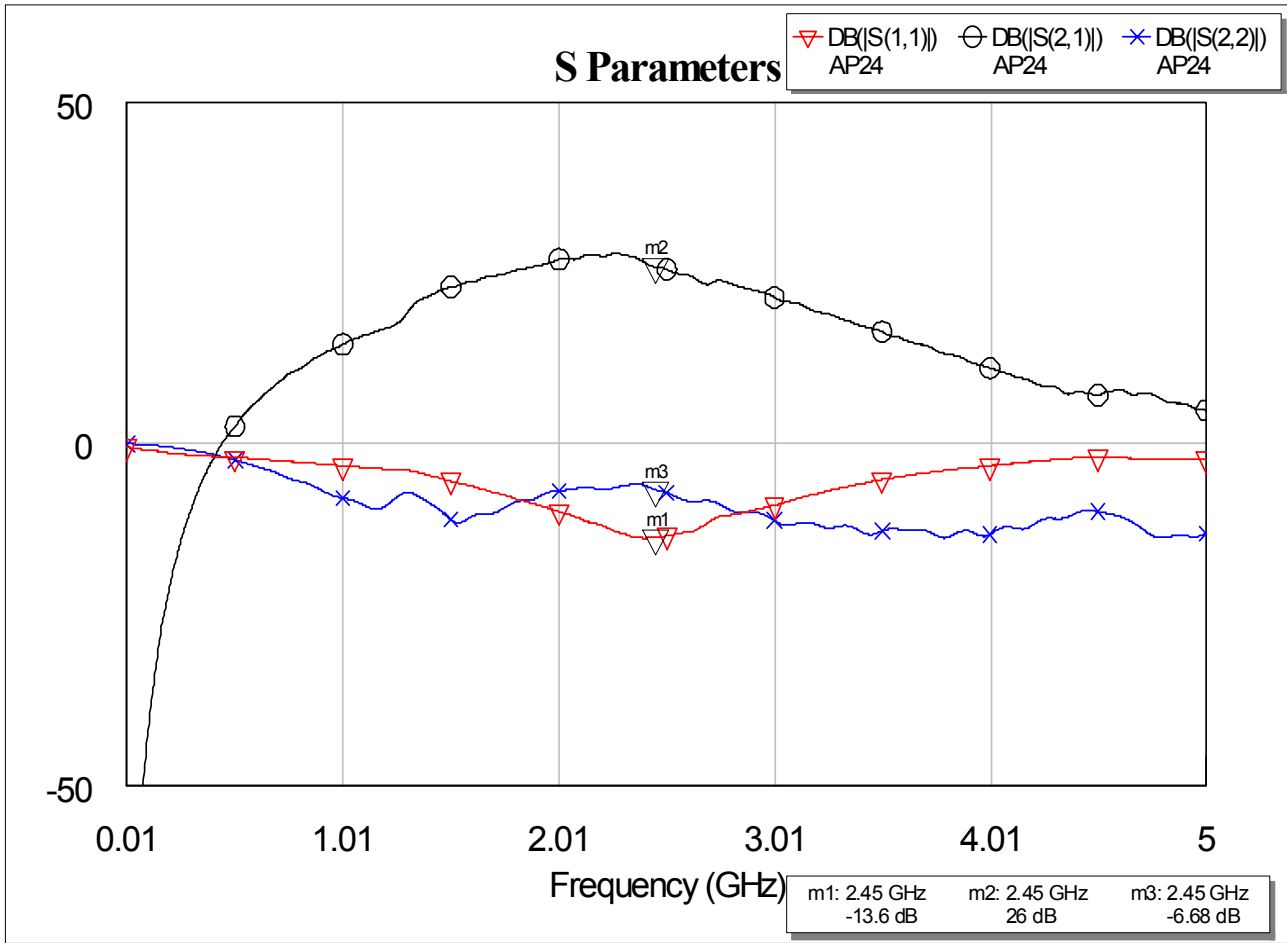
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Fig.3 – S Parameters



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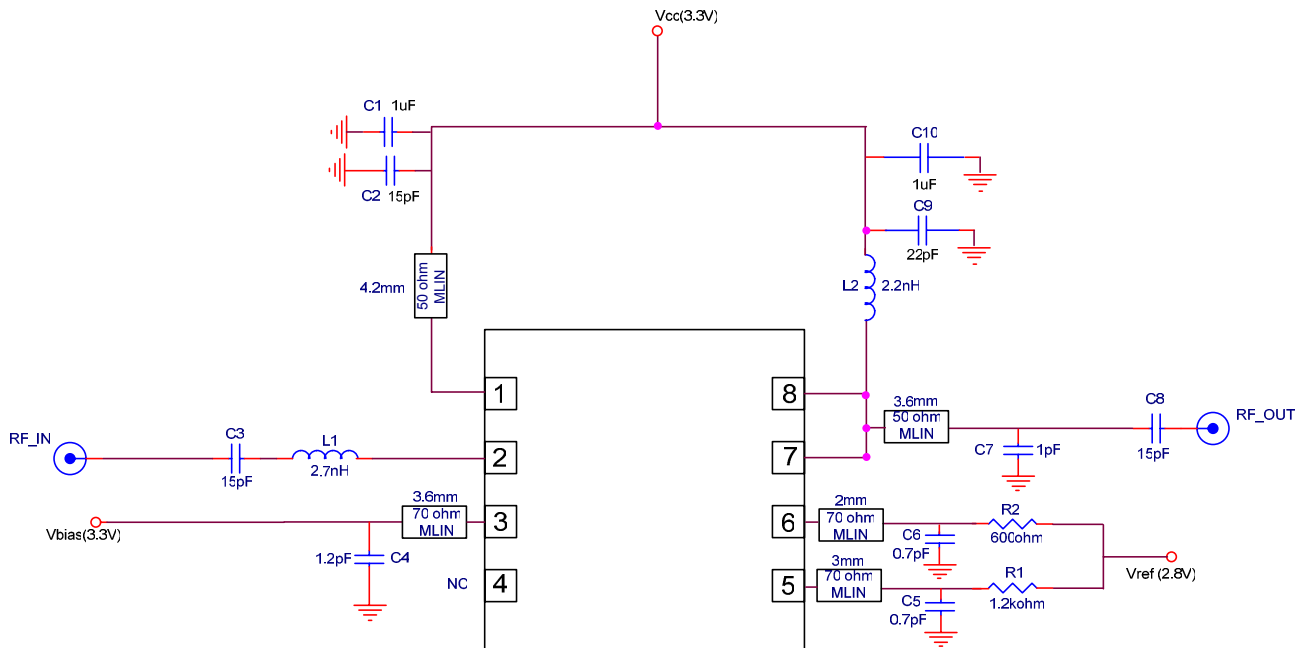
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EVB Circuit Diagram: WLAN Applications



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Data Charts: BT Applications

Fig.4

Pin & Icc vs. Pout

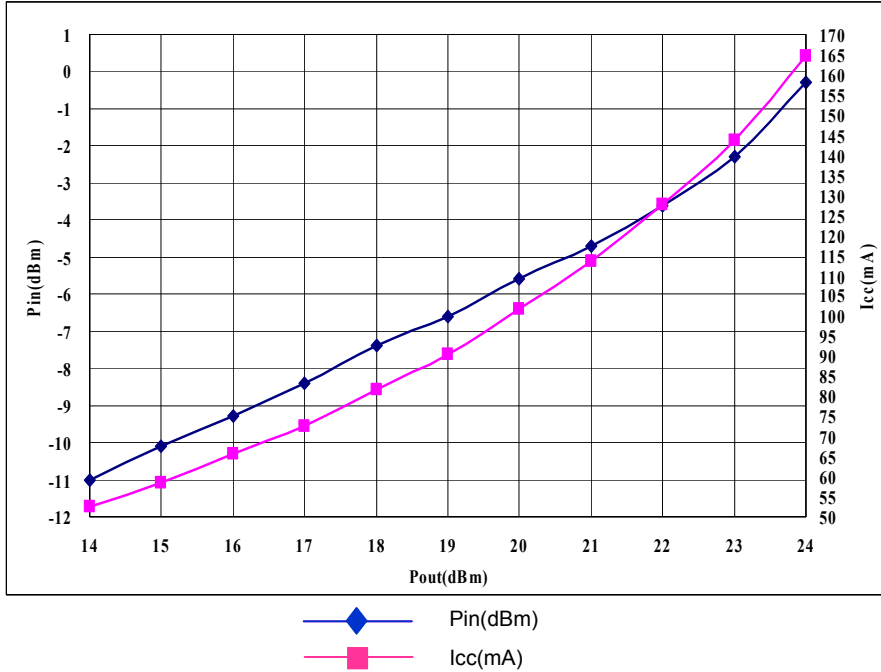
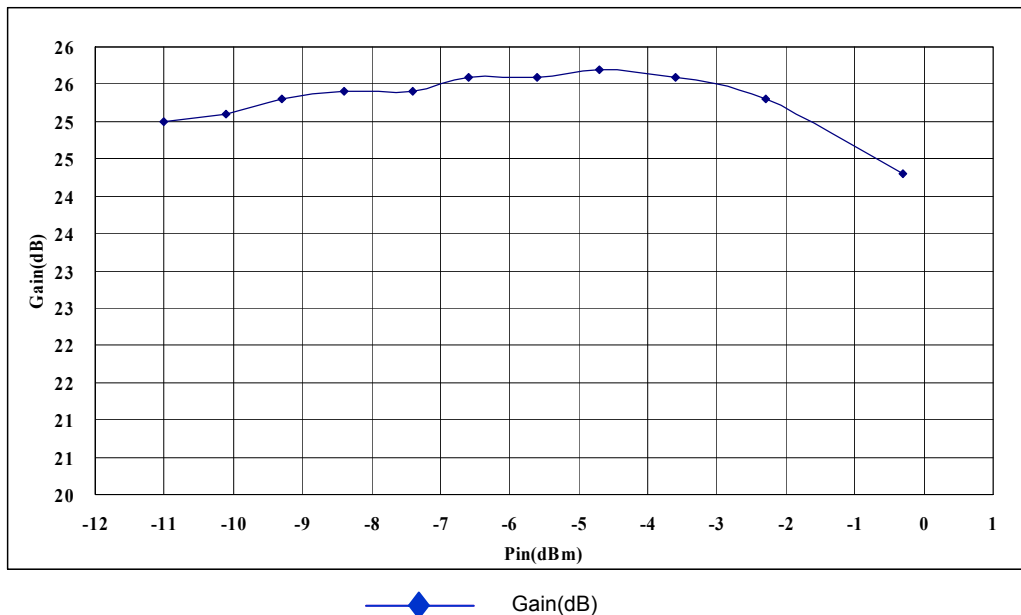


Fig.5

Power Gain vs. Pin



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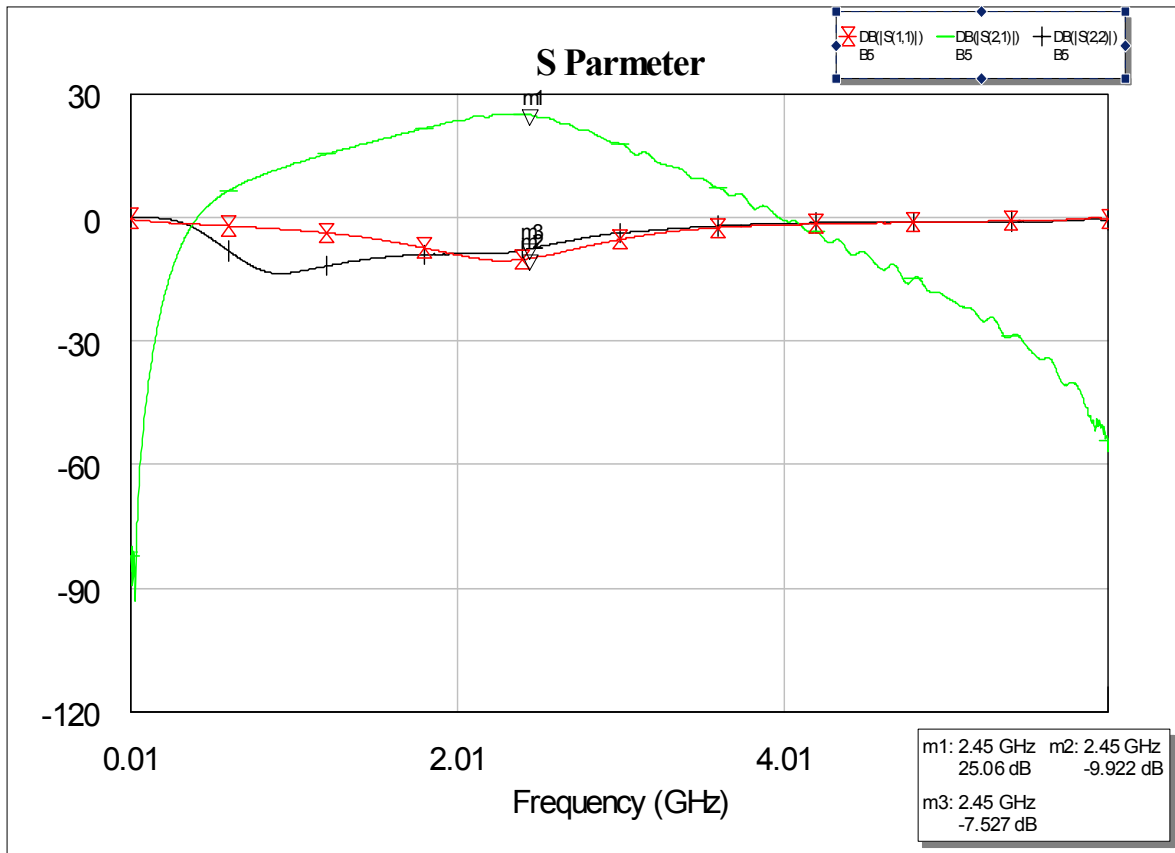
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Data Charts: BT Applications

Fig.6
S Parameters



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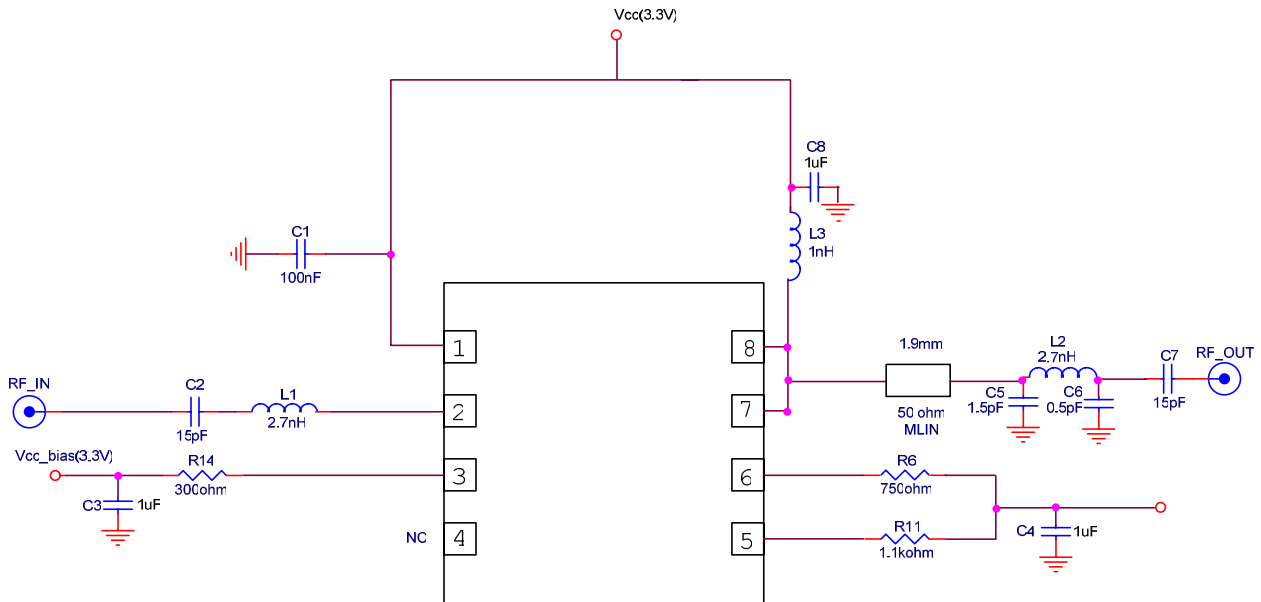
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EVB Circuit Diagram: BT Applications



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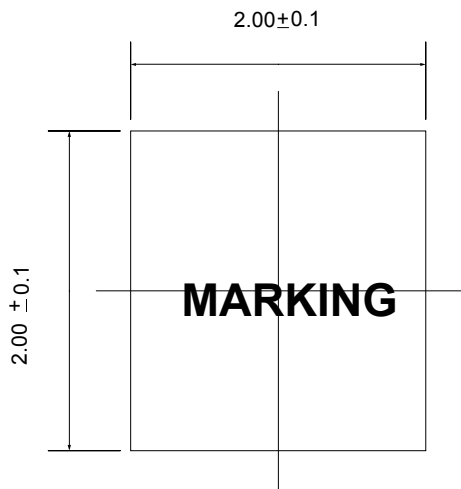
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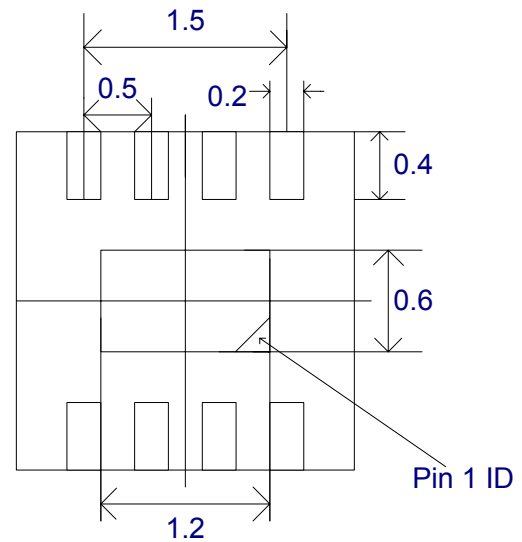
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Package Outline

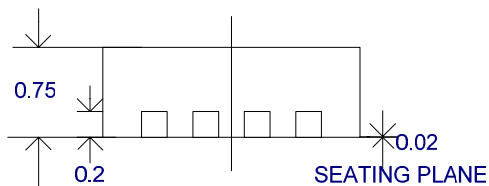
Top View



Bottom View



Side View



Unit: mm

Note :

1. Dimension and tolerance conform to ASME Y14.5M-1994.
2. Refer to JEDEC STD. MO-220 WEED-2 ISSUE B